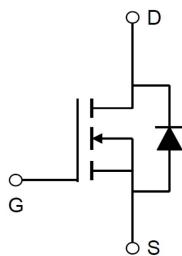
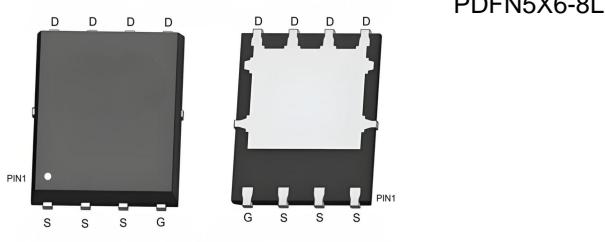


N-Channel 30V(D-S) MOSFET

Product summary		
V_{DS}	30	V
$R_{DS(ON)}$ (at $V_{GS}=10V$) Typ.	5	$m\Omega$
$I_D(T_c=25^\circ C)$	52	A

Features
<ul style="list-style-type: none"> High density cell design for low $R_{DS(ON)}$ Simple Drive Requirement Fast Switching Characteristic
Applications
<ul style="list-style-type: none"> Power management functions

Pin Configuration



Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAP52N03S	PDFN5X6-8L	13"	3000pcs

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current at $V_{GS}=10V$ ^A	$T_c=25^\circ C$	A
		$T_c=100^\circ C$	A
I_{DM}	Pulse Drain Current Tested ^B	125	A
E_{AS}	Single Pulse Avalanche Energy ^C	28.8	mJ
P_D	Power Dissipation @ $T_c=25^\circ C$	27	W
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient ^A	50	°C/W
$R_{\theta JC}$	Thermal Resistance-Junction to case ^A	4.6	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	--	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^B	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	--	5	6.3	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=15\text{A}$	--	7	8.5	$\text{m}\Omega$
V_{SD}	Forward Voltage	$I_{\text{S}}=1\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1	V
I_{S}	Continuous Diode Forward Current		--	--	30	A
Dynamic Parameters ^D						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=15\text{V}$ $f=1\text{MHz}$	--	814	977	pF
C_{oss}	Output Capacitance		--	498	598	pF
C_{rss}	Reverse Transfer Capacitance		--	41	49	pF
Q_{g}	Total Gate Charge	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=15\text{A}$ $V_{\text{GS}}=4.5\text{V}$	--	8	9.6	nC
Q_{gs}	Gate-Source Charge		--	2.4	2.9	nC
Q_{gd}	Gate-Drain Charge		--	3.2	3.8	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=15\text{V}$ $I_{\text{D}}=15\text{A}, R_{\text{G}}=3.3\Omega,$ $V_{\text{GS}}=10\text{V}$	--	7.1	8.5	nS
t_{r}	Turn-on Rise Time		--	40	48	nS
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	15	18	nS
t_{f}	Turn-off Fall Time		--	6	7.2	nS

A. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

B. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

C. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=24\text{A}$.

D. Guaranteed by design, not subject to production testing.

Typical Characteristics

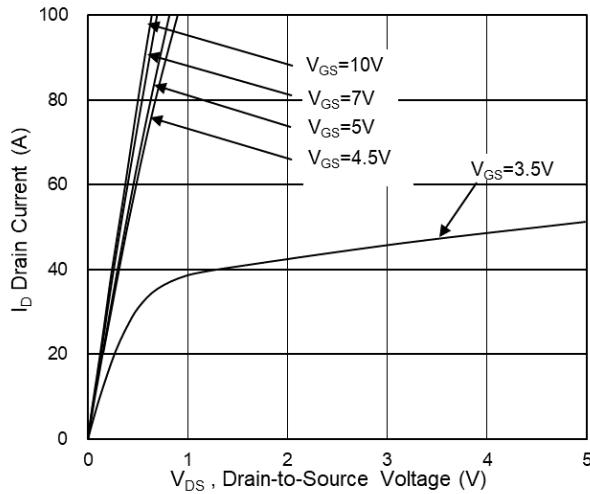


Fig.1 Typical Output Characteristics

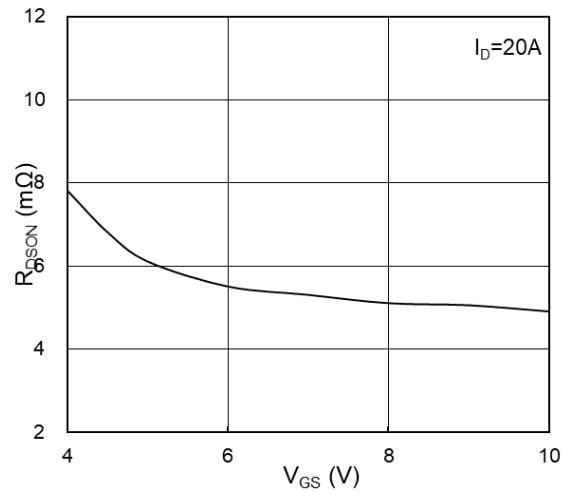


Fig.2 On-Resistance vs G-S Voltage

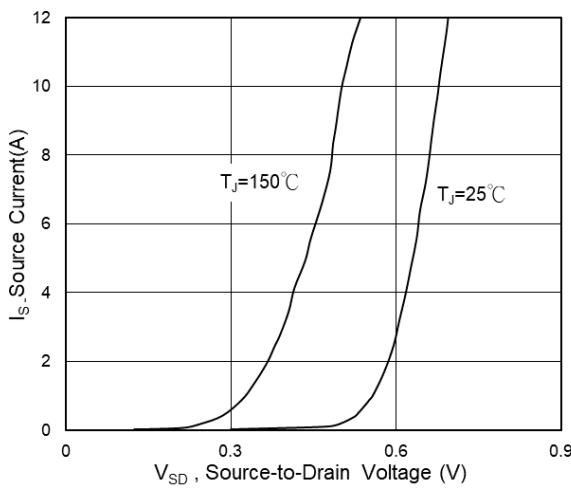


Fig.3 Source Drain Forward Characteristics

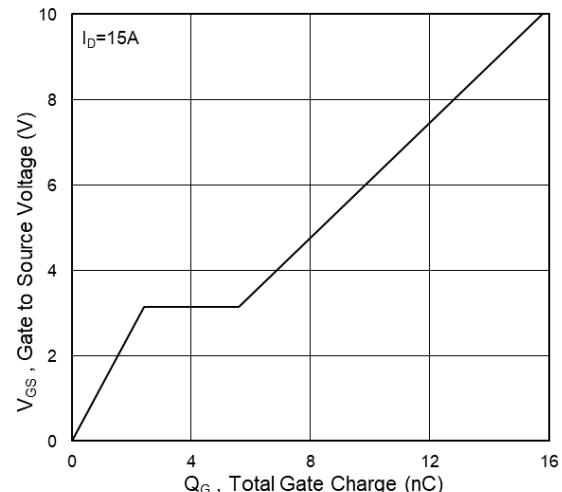


Fig.4 Gate-Charge Characteristics

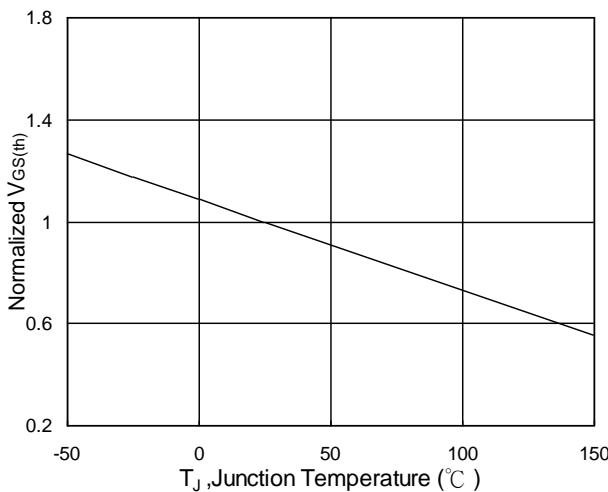


Fig.5 Normalized $V_{GS(th)}$ vs T_J

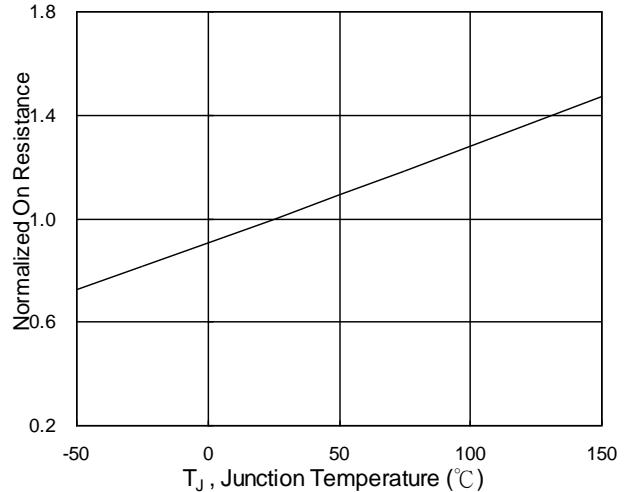
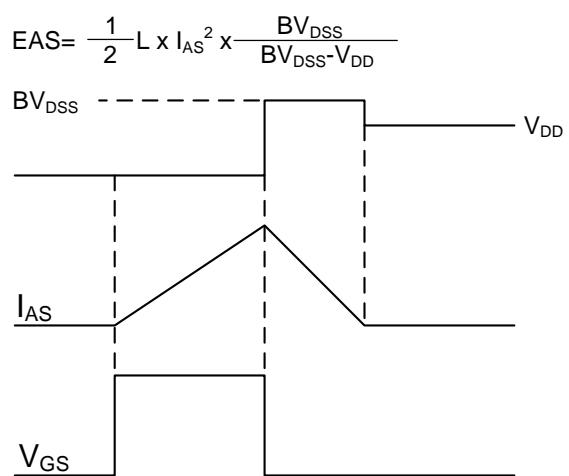
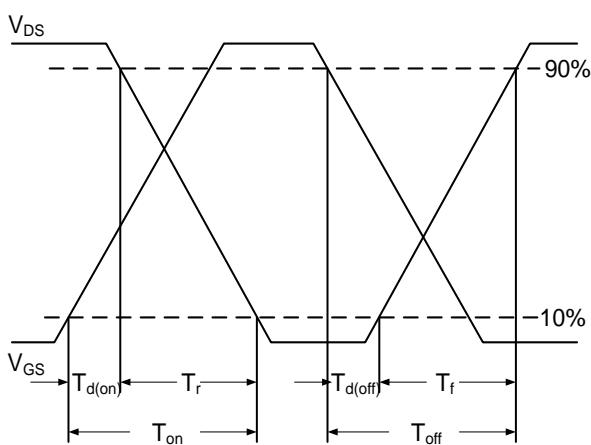
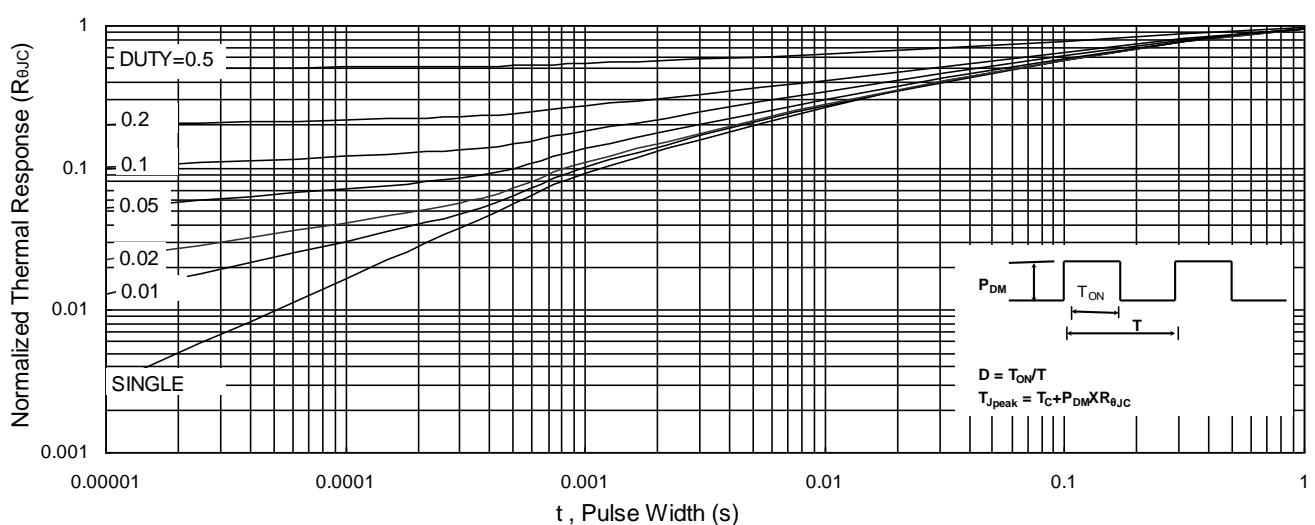
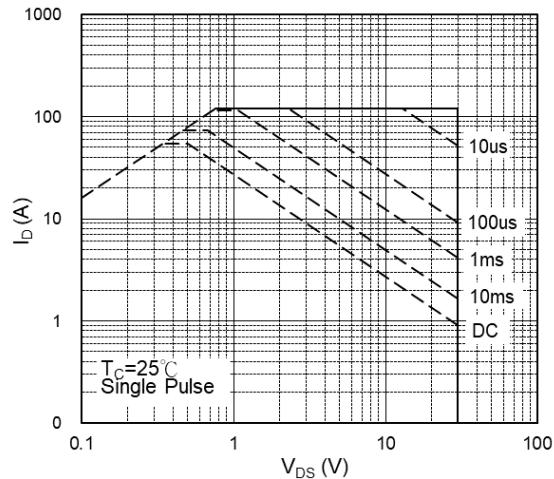
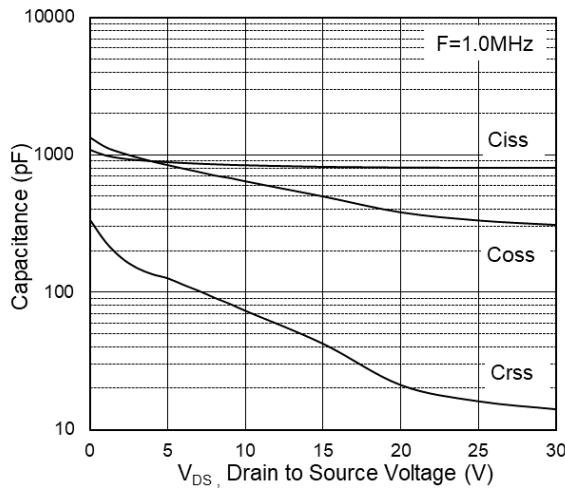
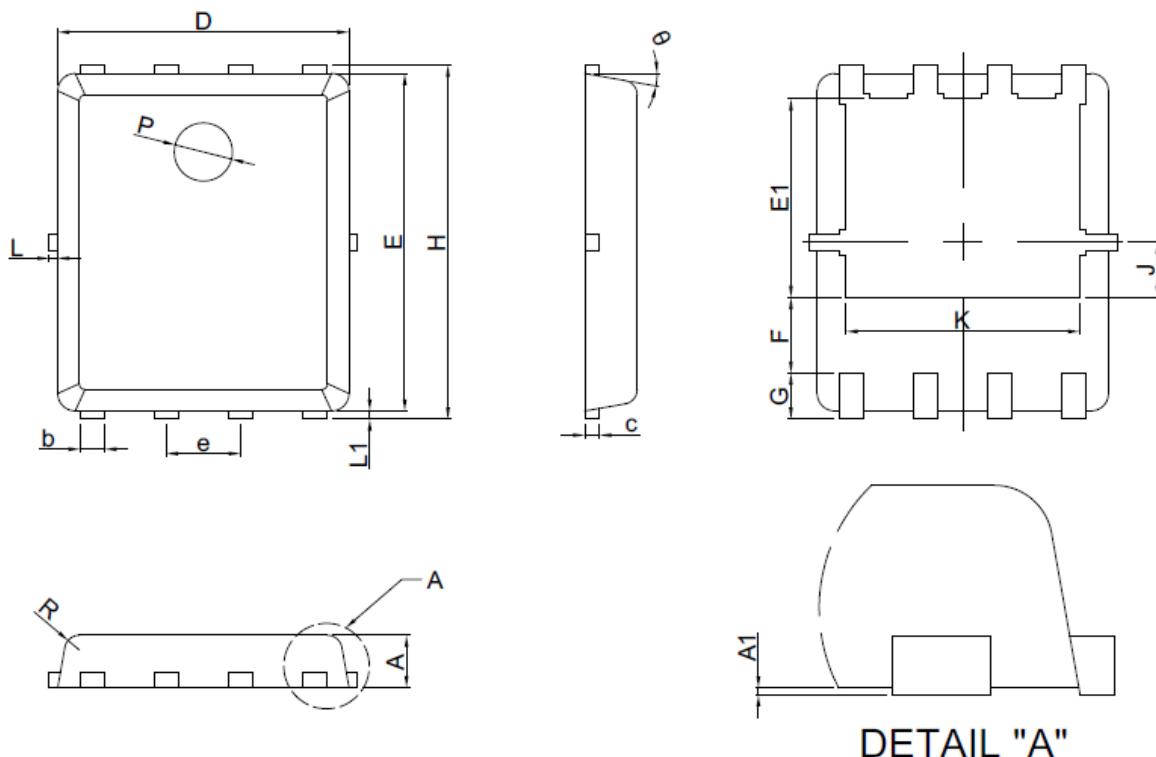


Fig.6 Normalized $R_{DS(on)}$ vs T_J

Typical Characteristics



PDFN5X6-8L Package Information



SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A _t	0.00	0.03	0.05
b	0.35	0.42	0.49
c	0.254REF		
D	4.90	5.00	5.10
F	1.40REF		
E	5.70	5.80	5.90
e	1.27BSC		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60REF		
K	4.00REF		
L	—	—	0.15
J	0.95BSC		
P	1.00REF		
E1	3.40REF		
θ	6°	10°	14°
R	0.25REF		